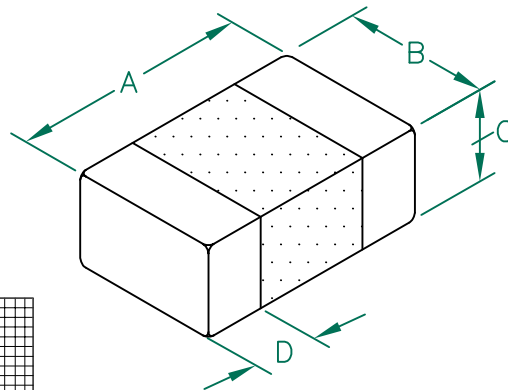


LI0805G301R-10

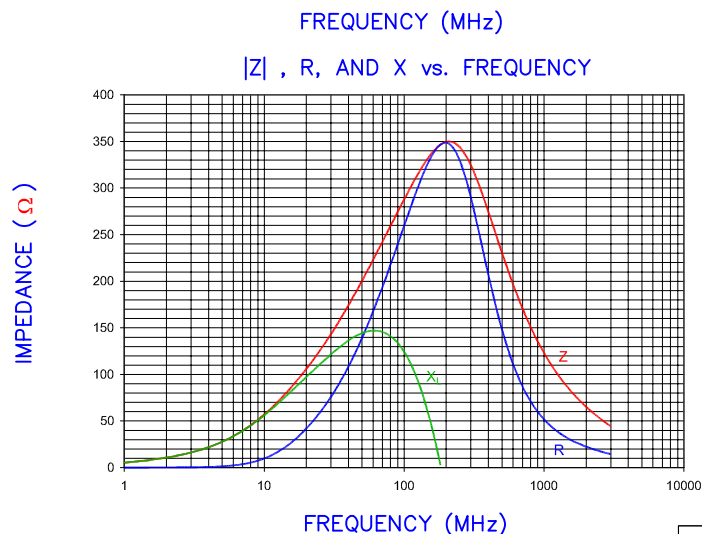
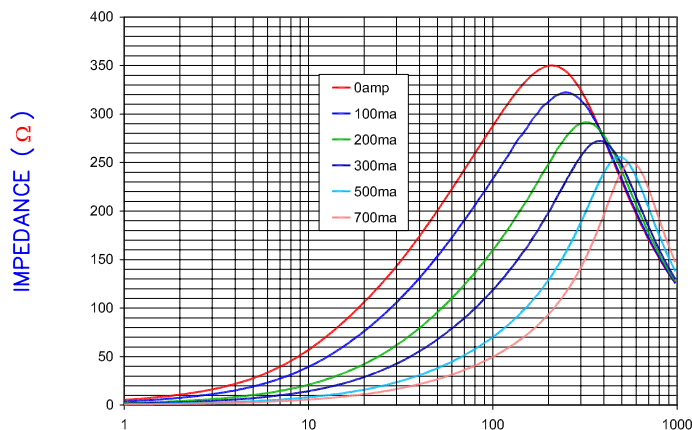
**UNCONTROLLED
DOCUMENT**

PHYSICAL DIMENSIONS:

A	2.00 [.079]	$\pm$ 0.20 [.008]
B	1.25 [.049]	$\pm$ 0.20 [.008]
C	0.90 [.035]	$\pm$ 0.20 [.008]
D	0.51 [.020]	$\pm$ 0.25 [.010]

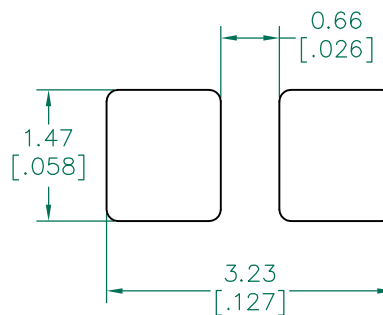


Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



AGILENT E4991A RF Impedance/Material Analyzer
HP 16194A Test Fixture. TEST REF. 3235

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [.030] to this dimension.)

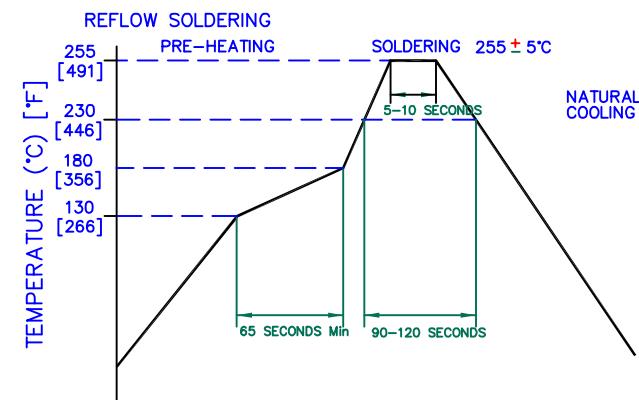
ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	300	
Minimum	225	
Maximum	375	0.2
		700 mA

NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
3. TERMINATION FINISH IS 100% TIN.
4. OPERATING TEMP. RANGE: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$. (INCLUDING SELF-HEATING)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].

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D	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	PROJECT/PART NUMBER:	REV
C	CHANGE TO PAPER TAPE	03/04/10	JUN	LI0805G301R-10	D
B	UPDATE COMPANY LOGO ADD ROHS SYM	07/21/08	JRK	DATE:	PART TYPE:
A	ORIGINAL DRAFT	04/13/04	JRK	04/13/04	CO-FIRE
REV	DESCRIPTION	DATE	INT	CAD #	DRAWN BY:
				LI0805G301R-10-D	JRK
				SCALE:	SHEET:
				NTS	2 of 2

RoHS
2002/95/EC